Flux paste model	Applicable alloys	Ratio	characteristic	remark
128	There is lead	10%-10.15%	Suitable for all tin-lead series, less residue and transparent, strong activity can be soldered QFN and other precision components, not easy to absorb moisture, long printing life (main recommendation)	
766	Lead-free, medium-temperature tin, bismuth silver	10.65-10.8%	It has little residue and is transparent, and has strong activity, which can weld precision components such as QFN, and is not easy to absorb moisture, and has a long printing life	
	Lead-free low-temperature tin-bismuth	10.%-10.15%		
008	0307/305	12%-12.3%	Transparent residue, can be used as LED, power board, control board, etc., printing life of about 8 hours	
506	0307/305	12%-12.3%	Less residue, strong activity, can do precision QFN (climb 75% to 85%), BGA effect is very good, printing life of about 8 hours, BGA void is small, suitable for products with BGA and QFN, can replace Aifa	
501	0307/305	11.4%-11.5%	The residue is very small, the solder joints are very bright, it can be used for precision QFN (climb 80% to 90%), and the printing life is about 24 hours, which can replace Qianzhu	
223	0307/305	12.6%-12.8%	It can be used for precision QFN, which can basically be climbed and the printing life is about 48 hours, which is aimed at customers with very high requirements for QFN climbing	

Product Code	Applicable Alloy	Proportion In Percentage	Special Characteristics	remark
128	Leaded Solder Flux	10%-10.15%	Suitable for all tin-lead series, less residue and transparent, strong activity can be soldered QFN and other precision components, not easy to absorb moisture, long printing life (main recommendation)	
766	Lead-free, medium-temperature tin, bismuth silver	10.65-10.8%	It has little residue and is transparent, and has strong activity, which can weld precision components such as QFN, and is not easy to absorb moisture, and has a long printing life	
	Lead-free low-temperature tin-bismuth	10.%-10.15%		
008	Leaded Free Solder Flux 0307/305	12%-12.3%	Transparent residue, can be used as LED, power board, control board, etc., printing life of about 8 hours	
506	0307/305	12%-12.3%	Less residue, strong activity, can do precision QFN (climb 75% to 85%), BGA effect is very good, printing life of about 8 hours, BGA void is small, suitable for products with BGA and QFN, can replace Aifa	
501	0307/305	11.4%-11.5%	The residue is very small, the solder joints are very bright, it can be used for precision QFN (climb 80% to 90%), and the printing life is about 24 hours, which can replace Qianzhu	
223	0307/305	12.6%-12.8%	It can be used for precision QFN, which can basically be climbed and the printing life is about 48 hours, which is aimed at customers with very high requirements for QFN climbing	